Bulletin PD-21064 rev. B 11/06

International
IOR Rectifier

30ETH06SPbF
30ETH06-1PbF

Hyperfast Rectifier

Features

- Hyperfastfast Recovery Time
- Low Forward Voltage Drop
- Low Leakage Current
- 125°C Operating Junction Temperature
- Dual Diode Center Tap
- Lead-Free ("PbF" suffix)

t_{rr} = 28ns typ.
$I_{F(AV)}$ = 30Amp
V_R = 600V

Description/ Applications

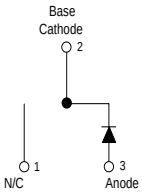
State of the art Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, Hyperfast recover time, and soft recovery.
The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.
These devices are intended for use in PFC Boost stage in the AC-DC section of SMPS, inverters or as freewheeling diodes.
The IR extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

Absolute Maximum Ratings

	Parameters		Max	Units
V_{RRM}	Peak Repetitive Reverse Voltage		600	V
$I_{F(AV)}$	Average Rectifier Forward Current	@ T_C = 103°C	30	A
I_{FSM}	Non Repetitive Peak Surge Current	@ T_J = 25°C	200	
T_J	Operating Junction Temperature		- 65 to 125	°C
T_{STG}	Operating Storage Temperature		- 65 to 150	

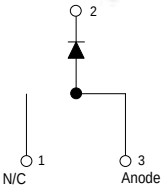
Case Styles

30ETH06SPbF



D^2PAK

30ETH06-1PbF



TO-262

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

Parameters		Min	Typ	Max	Units	Test Conditions
V_{BR}, V_r	Breakdown Voltage, Blocking Voltage	600	-	-	V	I_R = 100µA
V_F	Forward Voltage	-	2.0	2.6	V	I_F = 30A, T_J = 25°C
		-	1.34	1.75	V	I_F = 30A, T_J = 150°C
I_R	Reverse Leakage Current	-	0.3	50	µA	V_R = V_R Rated
		-	60	500	µA	T_J = 150°C, V_R = V_R Rated
C_T	Junction Capacitance	-	33	-	pF	V_R = 600V
L_S	Series Inductance	-	8.0	-	nH	Measured lead to lead 5mm from package body

Dynamic Recovery Characteristics @ T_J = 25°C (unless otherwise specified)

Parameters		Min	Typ	Max	Units	Test Conditions	
t_{rr}	Reverse Recovery Time	-	28	35	ns	I_F = 1.0A, di_F/dt = 50A/µs, V_R = 30V	
		-	31	-		T_J = 25°C	I_F = 30A V_R = 200V di_F/dt = 200A/µs
			77	-		T_J = 125°C	
I_{RRM}	Peak Recovery Current	-	3.5	-	A	T_J = 25°C	
		-	7.7	-		T_J = 125°C	
Q_{rr}	Reverse Recovery Charge	-	65	-	nC	T_J = 25°C	
		-	345	-		T_J = 125°C	

Thermal - Mechanical Characteristics

Parameters			Min	Typ	Max	Units
T_J	Max. Junction Temperature Range		- 65	-	125	°C
T_{Stg}	Max. Storage Temperature Range		- 65	-	150	
R_{thJC}	Thermal Resistance, Junction to Case	Per Leg	-	0.7	1.1	°C/W
R_{thJA} ①	Thermal Resistance, Junction to Ambient	Per Leg	-	-	70	
R_{thCS} ②	Thermal Resistance, Case to Heatsink		-	0.2	-	
	Weight		-	2.0	-	g
			-	0.07	-	(oz)
	Mounting Torque		6.0	-	12	Kg-cm
			5.0	-	10	lbf.in
	Marking Device		30ETH06S		Case style D^2Pak	
			30ETH06-1		Case style TO-262	

① Typical Socket Mount
② Mounting Surface, Flat, Smooth and Greased

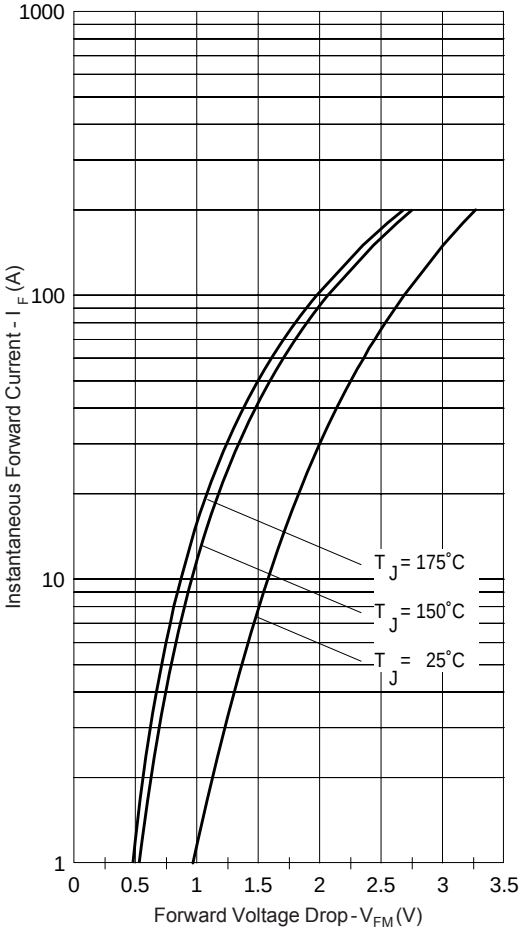


Fig. 1 - Typical Forward Voltage Drop Characteristics

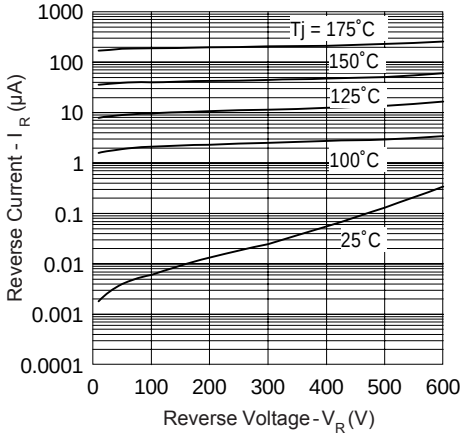


Fig. 2 - Typical Values Of Reverse Current Vs. Reverse Voltage

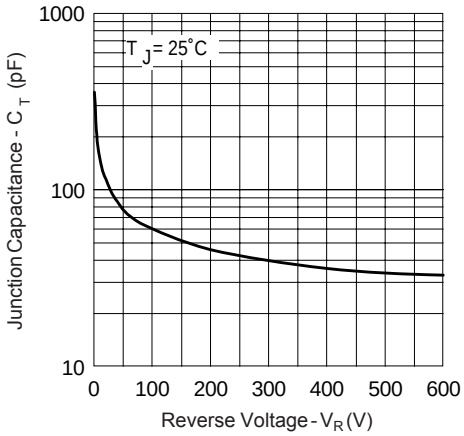


Fig. 3 - Typical Junction Capacitance Vs. Reverse Voltage

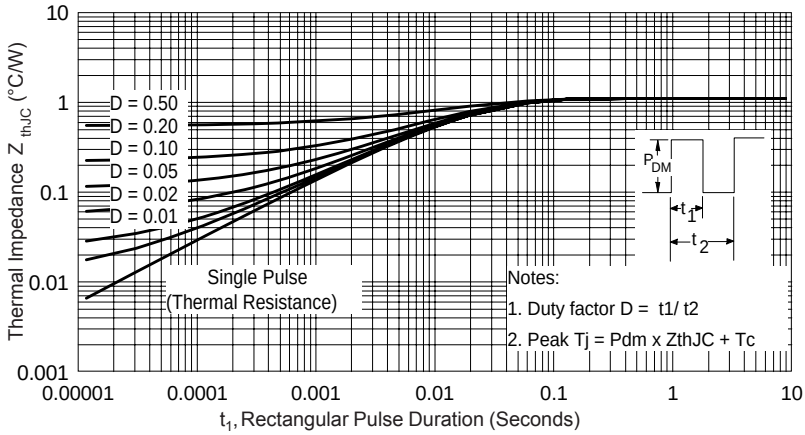


Fig. 4 - Max. Thermal Impedance Z_{thJC} Characteristics

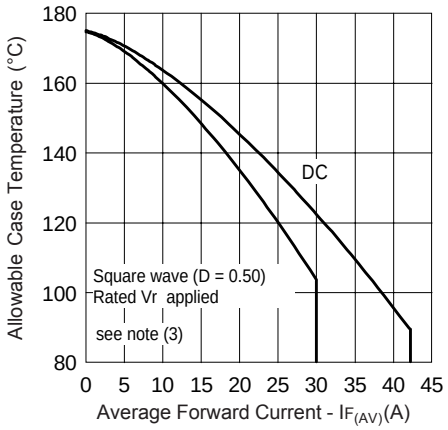


Fig. 5 - Max. Allowable Case Temperature Vs. Average Forward Current

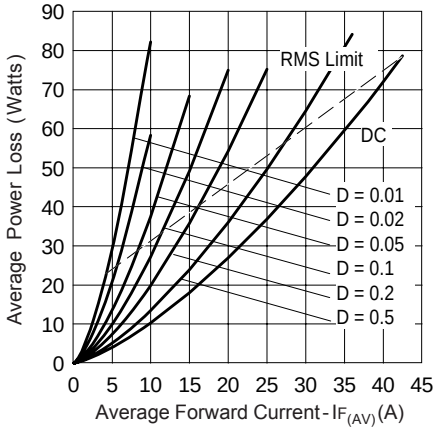


Fig. 6 - Forward Power Loss Characteristics

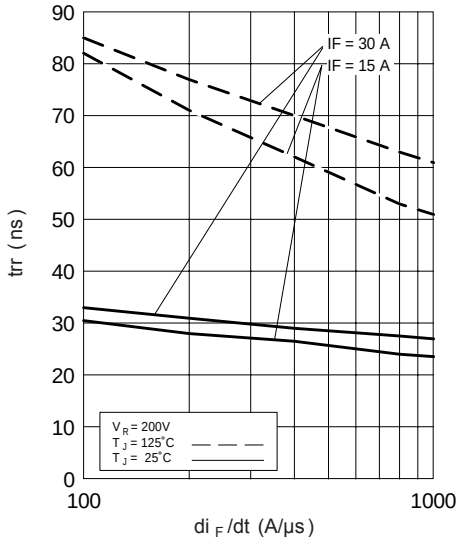


Fig. 7 - Typical Reverse Recovery vs. di_F/dt

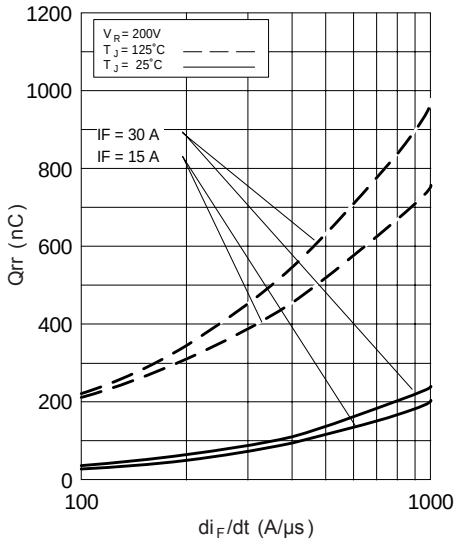


Fig. 8 - Typical Stored Charge vs. di_F/dt

(3) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
Pd = Forward Power Loss = $I_{F(AV)} \times V_{FM} @ (I_{F(AV)} / D)$ (see Fig. 6);
Pd_{REV} = Inverse Power Loss = $V_{R1} \times I_R (1 - D)$; $I_R @ V_{R1}$ = rated V_R

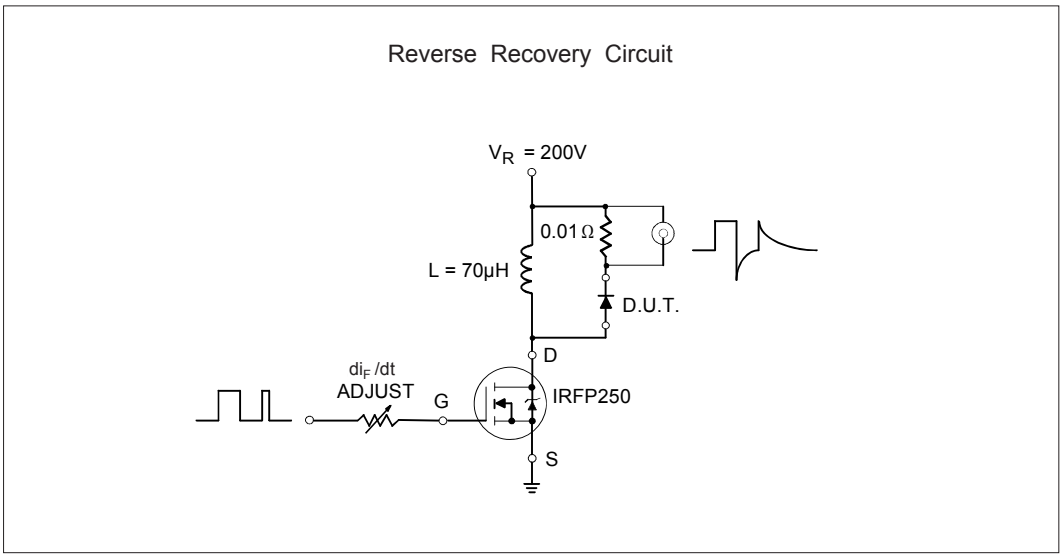
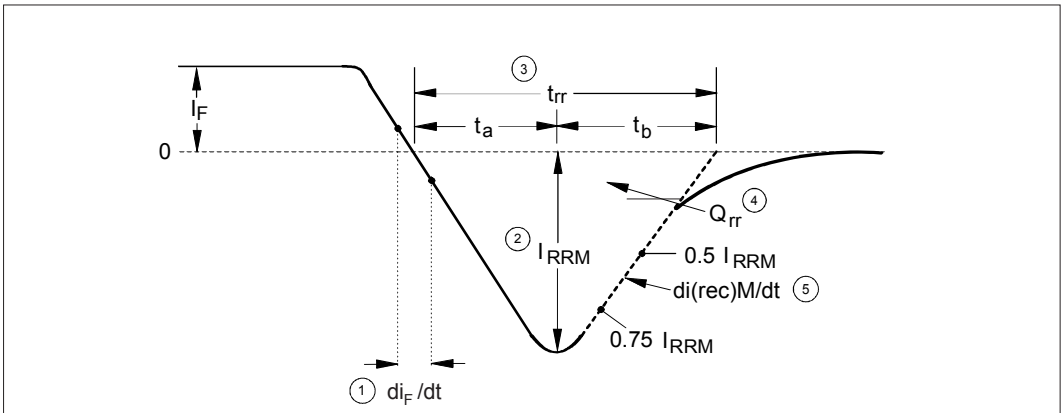


Fig. 9- Reverse Recovery Parameter Test Circuit



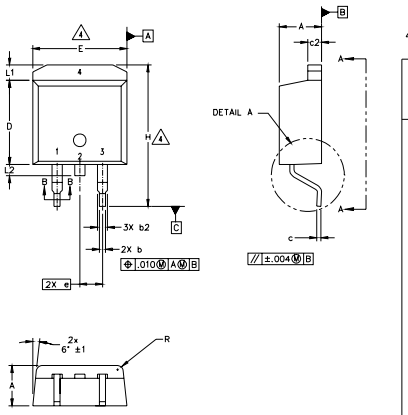
1. di_F/dt - Rate of change of current through zero crossing
2. I_{RRM} - Peak reverse recovery current
3. t_{rr} - Reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current
4. Q_{rr} - Area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

5. $di_{(rec)M}/dt$ - Peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

Outline Table



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
5. CONTROLLING DIMENSION: INCH.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	0.00	0.254	.000	.010	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	4
b2	1.14	1.78	.045	.070	
c	0.38	0.74	.015	.029	
c1	0.38	0.58	.015	.023	4
c2	1.14	1.65	.045	.065	
D	8.51	9.65	.335	.380	3
D1	6.86		.270		
E	9.65	10.67	.380	.420	3
E1	6.22		.245		
e	2.54 BSC		.100 BSC		
H	14.61	15.88	.575	.625	
L	1.78	2.79	.070	.110	
L1		1.65		.065	
L2	1.27	1.78	.050	.070	
L3	0.25 BSC		.010 BSC		
L4	4.78	5.28	.188	.208	
m	17.78		.700		
m1	8.89		.350		
n	11.43		.450		
o	2.08		.082		
p	3.81		.150		
R	0.51	0.71	.020	.028	
θ	90°	93°	90°	93°	

LEAD ASSIGNMENTS

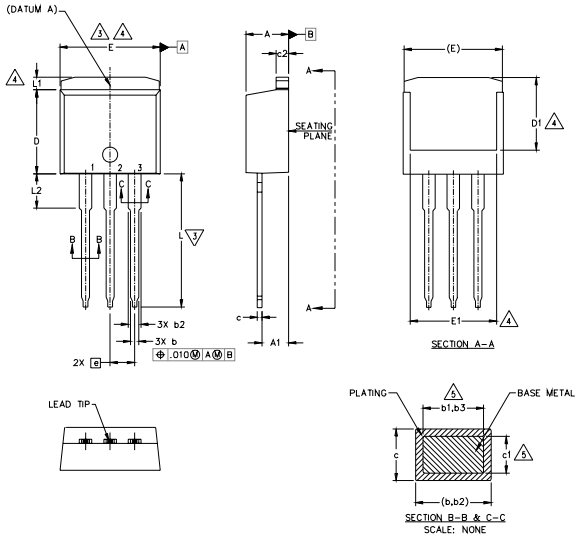
HEXFET
1.– GATE
2, 4.– DRAIN
3.– SOURCE

IGBTs, CoPACK
1.– GATE
2, 4.– COLLECTOR
3.– EMITTER

DIODES
1.– ANODE *
2, 4.– CATHODE
3.– ANODE

* PART DEPENDENT.

Conform to JEDEC outline D^2Pak (SMD-220)
Dimensions in millimeters and (inches)



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
5. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
6. CONTROLLING DIMENSION: INCH.
7. – OUTLINE CONFORM TO JEDEC TO-262 EXCEPT A1(max.), b(min.) AND D1(min.) WHERE DIMENSIONS DERIVED THE ACTUAL PACKAGE OUTLINE.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1	2.03	3.02	.080	.119	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	5
b2	1.14	1.78	.045	.070	
b3	1.14	1.73	.045	.068	5
c	0.38	0.74	.015	.029	
c1	0.38	0.58	.015	.023	5
c2	1.14	1.65	.045	.065	
D	8.38	9.65	.330	.380	3
D1	6.86	–	.270	–	4
E	9.65	10.67	.380	.420	3,4
E1	6.22	–	.245		4
e	2.54 BSC		.100 BSC		
L	13.46	14.10	.530	.555	
L1	–	1.65	–	.065	4
L2	3.56	3.71	.140	.146	

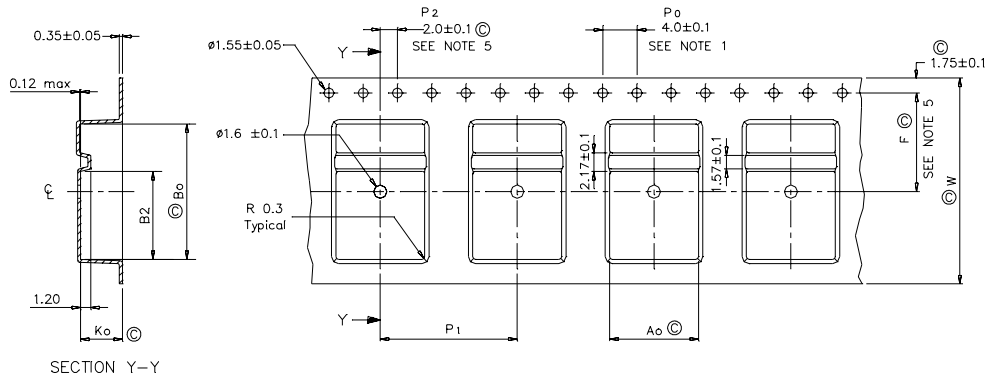
LEAD ASSIGNMENTS

HEXFET
1.– GATE
2.– DRAIN
3.– SOURCE
4.– DRAIN

IGBTs, CoPACK
1.– GATE
2.– COLLECTOR
3.– EMITTER
4.– COLLECTOR

Modified JEDEC outline TO-262
Dimensions in millimeters and (inches)

Tape & Reel Information



Ao	10.50 +/– 0.1
Bo	15.80 +/– 0.1
B2	10.25 +/– 0.1
Ko	4.90 +/– 0.1
F	11.50 +/– 0.1
P1	16.00 +/– 0.1
W	24.00 +/– 0.3

NOTES:
1.0 10 SPROCKET HOLE PITH CUMULATIVE TOLERANCE ±.02
2.0 CAMBER NOT TO EXCEED 1mm in 100mm
3.0 MATERIAL: CONDUCTIVE BLACK STYRENIC ALLOY
4.0 Ko MEASURED FROM A PLANE ON THE INSIDE BOTTOM OF THE POCKET TO THE TOP SURFACE OF THE CARRIER
5.0 MEASURED FROM CENTRELINE OF SPROCKET HOLE TO CENTRELINE OF POCKET
6.0 VENDOR: (OPTIONAL)
7.0 MUST ALSO MEET REQUIREMENTS OF EIA STANDAR #EIA–481A TAPING OF SURFACE MOUNT COMPONENTS FOR AUTOMATIC PLACEMENT
8.0 SURFACE RESISTIVITY OF MOLDED MATL. MUST MEASURE LESS OR EQUAL TO 10^6 OHMS PER SQUARE. MEASURED IN ACCORDANCE TO PROCEDURE GIVEN IN ASTM D–257 & ASTM D–991
9.0 TOTAL LENGTH PER REEL MUST BE 45 METERS
10.0 © CRITICAL

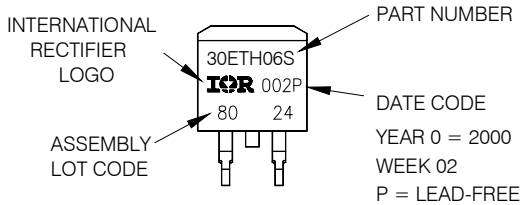
Dimensions in millimeters and (inches)

Part Marking Information

D²PAK

EXAMPLE: THIS IS A 30ETH06S
LOT CODE 8024
ASSEMBLED ON WW 02, 2000

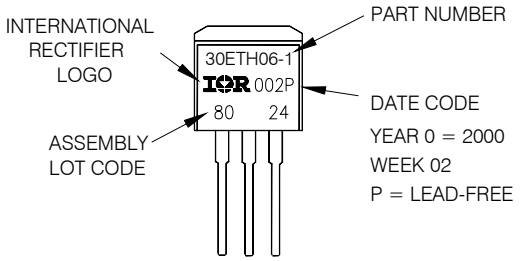
Note: "P" in assembly line position indicates "Lead–Free"



TO-262

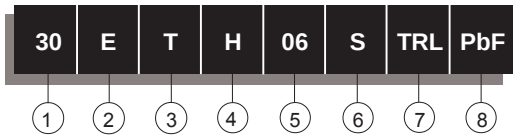
EXAMPLE: THIS IS A 30ETH06-1
LOT CODE 8024
ASSEMBLED ON WW 02, 2000

Note: "P" in assembly line position indicates "Lead–Free"



Ordering Information Table

Device Code



1	-	Current Rating (30 = 30A)
2	-	E = Single Diode
3	-	T = TO-220, D^2Pak
4	-	H = HyperFast Recovery
5	-	Voltage Rating (06 = 600V)
6	-	• S = D^2Pak
		• -1 = TO-262
7	-	• none = Tube (50 pieces)
		• TRL = Tape & Reel (Left Oriented, for D^2PAk package)
		• TRR = Tape & Reel (Right Oriented, for D^2PAk package)
8	-	• none = Standard Production
		• PbF = Lead-Free

Data and specifications subject to change without notice.
This product has been designed and qualified for Industrial Level and Lead-Free.
Qualification Standards can be found on IR's Web site.

International
IOR Rectifier

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